

SIPMOS® Small-Signal-Transistor

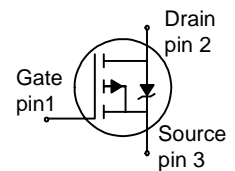
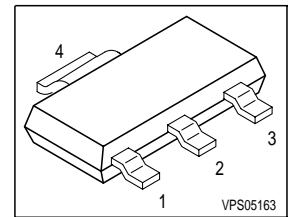
Feature

- P-Channel
- Enhancement mode
- Avalanche rated
- dv/dt rated

Product Summary

V_{DS}	-60	V
$R_{DS(on)}$	0.3	Ω
I_D	-1.9	A

SOT-223



Type	Package	Ordering Code
BSP 170 P	SOT-223	Q67041-S4018

Maximum Ratings, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current	I_D		A
$T_A=25^\circ\text{C}$		-1.9	
$T_A=70^\circ\text{C}$		-1.5	
Pulsed drain current	$I_{D\text{ puls}}$	-7.6	
$T_A=25^\circ\text{C}$			
Avalanche energy, single pulse	E_{AS}	70	mJ
$I_D=-1.9\text{ A}$, $V_{DD}=-25\text{V}$, $R_{GS}=25\Omega$			
Avalanche energy, periodic limited by T_{jmax}	E_{AR}	0.18	
Reverse diode dv/dt	dv/dt	-6	kV/ μs
$I_S=-1.9\text{A}$, $V_{DS}=-48\text{V}$, $di/dt=-200\text{A}/\mu\text{s}$, $T_{jmax}=150^\circ\text{C}$			
Gate source voltage	V_{GS}	± 20	V
Power dissipation	P_{tot}	1.8	W
$T_A=25^\circ\text{C}$			
Operating and storage temperature	T_j, T_{stg}	-55... +150	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/150/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - soldering point (Pin 4)	R_{thJS}	-	-	20	K/W
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ¹⁾	R_{thJA}	-	-	110 70	

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0, I_D=-250\mu A$	$V_{(BR)DSS}$	-60	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=-250\mu A$	$V_{GS(th)}$	-2.1	-3	-4	
Zero gate voltage drain current $V_{DS}=-60V, V_{GS}=0, T_j=25\text{ °C}$ $V_{DS}=-60V, V_{GS}=0, T_j=125\text{ °C}$	I_{DSS}	-	-0.1 -10	-1 -100	μA
Gate-source leakage current $V_{GS}=-20V, V_{DS}=0$	I_{GSS}	-	-10	-100	
Drain-source on-state resistance $V_{GS}=-10V, I_D=-1.9$	$R_{DS(on)}$	-	0.24	0.3	Ω

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic Characteristics

Transconductance	g_{fs}	$V_{DS} \leq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = -1.9$	1.4	2.8	-	S
Input capacitance	C_{iss}	$V_{GS} = 0, V_{DS} = -25V,$ $f = 1MHz$	-	328	410	pF
Output capacitance	C_{oss}		-	105	135	
Reverse transfer capacitance	C_{rss}		-	38	48	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -30V, V_{GS} = -10V,$ $I_D = -1.9A, R_G = 6\Omega$	-	14	21	ns
Rise time	t_r		-	28	42	
Turn-off delay time	$t_{d(off)}$		-	92	138	
Fall time	t_f		-	60	90	

Gate Charge Characteristics

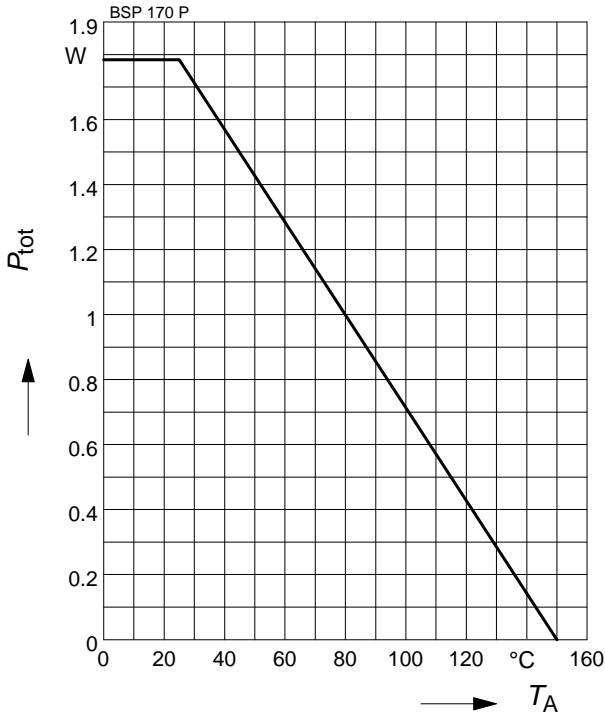
Gate to source charge	Q_{gs}	$V_{DD} = -48V, I_D = -1.9A$	-	-1.4	-2.1	nC
Gate to drain charge	Q_{gd}		-	-3.6	-5.4	
Gate charge total	Q_g	$V_{DD} = -48V, I_D = -1.9A,$ $V_{GS} = 0 \text{ to } -10V$	-	-12.5	-16	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = -48V, I_D = -1.9A$	-	-3.85	-	V

Reverse Diode

Inverse diode continuous forward current	I_S	$T_A = 25^\circ\text{C}$	-	-	-1.9	A
Inverse diode direct current, pulsed	I_{SM}		-	-	-7.6	
Inverse diode forward voltage	V_{SD}	$V_{GS} = 0, I_F = -1.9A$	-	-0.85	-1.1	V
Reverse recovery time	t_{rr}	$V_R = -30V, I_F = I_S,$ $di_F/dt = -100A/\mu s$	-	36	54	ns
Reverse recovery charge	Q_{rr}	$V_R = -30V, I_F = I_S,$ $di_F/dt = 100A/\mu s$	-	41	62	nC

1 Power dissipation

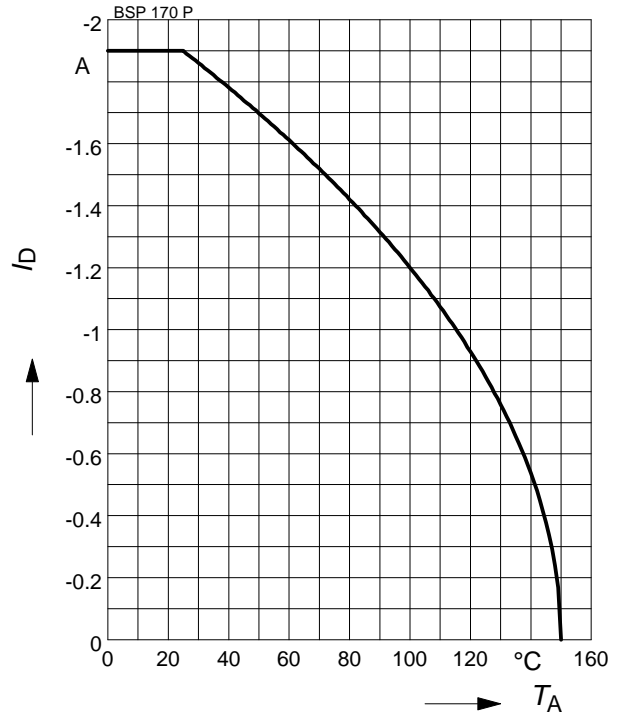
$$P_{tot} = f(T_A)$$



2 Drain current

$$I_D = f(T_A)$$

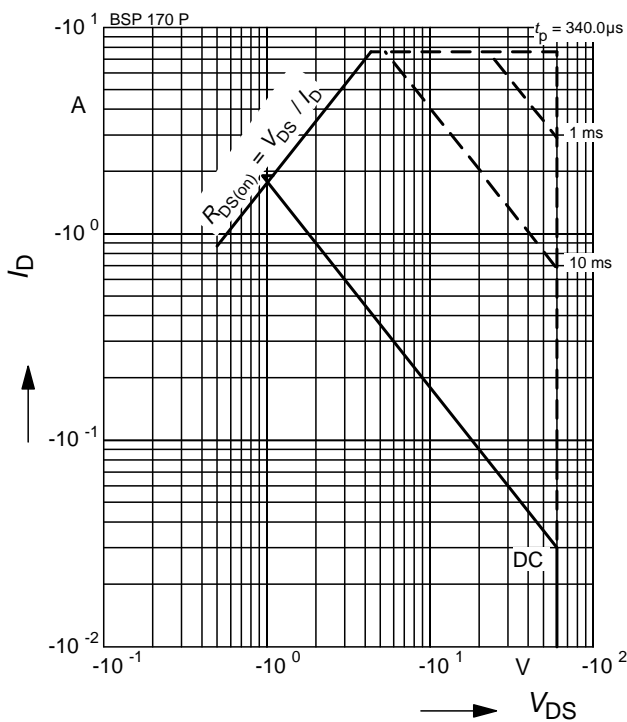
parameter: $|V_{GS}| \geq 10V$



3 Safe operating area

$$I_D = f(V_{DS})$$

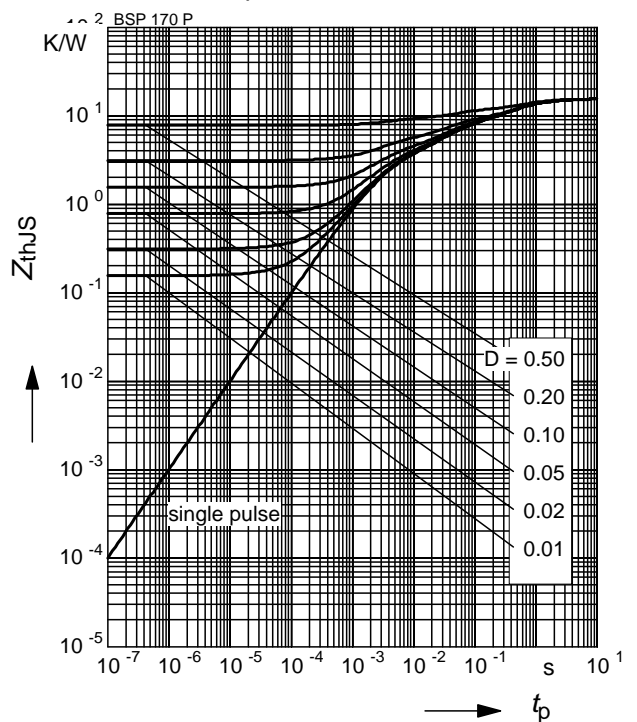
parameter: $D = 0, T_A = 25^\circ C$



4 Transient thermal impedance

$$Z_{thJS} = f(t_p)$$

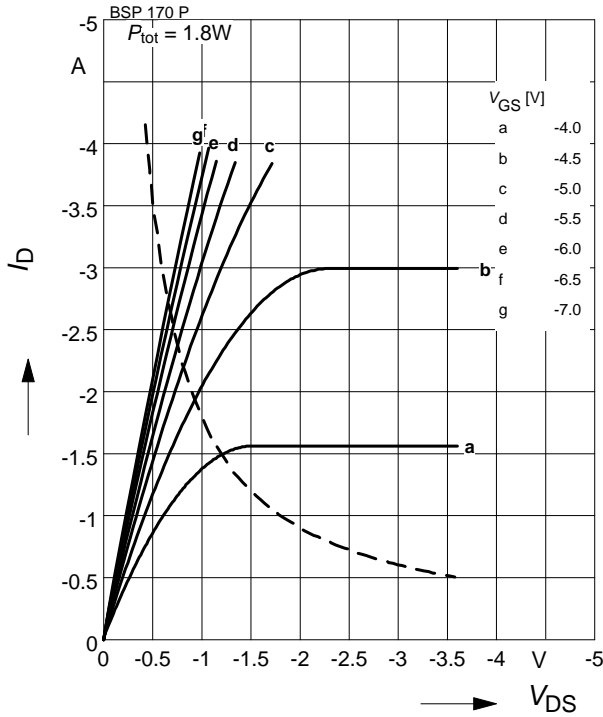
parameter: $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

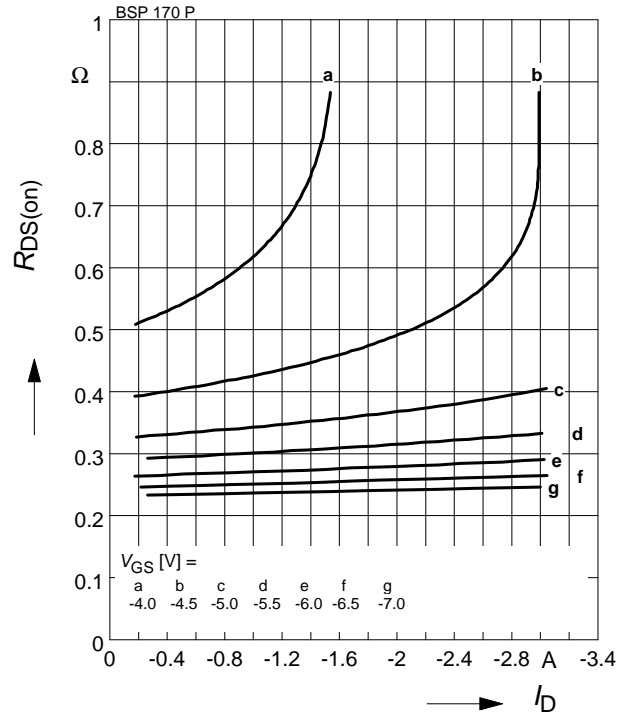
parameter: $t_p = 80 \mu\text{s}$



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

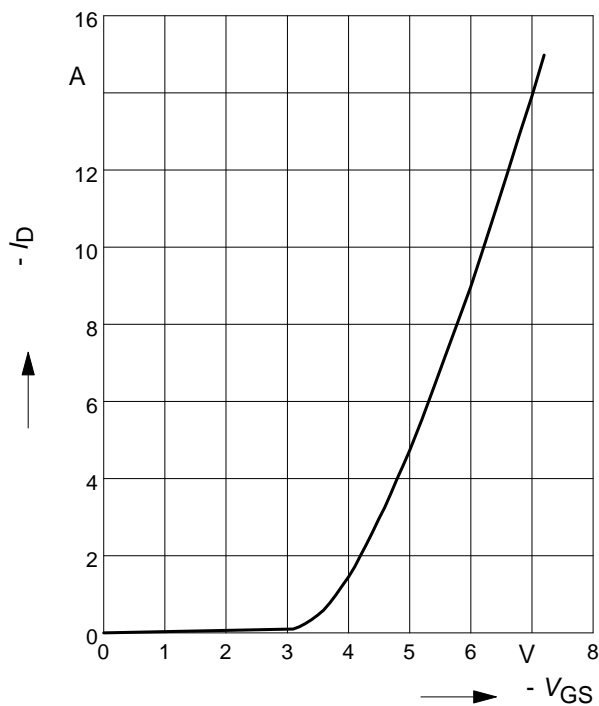
parameter: V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

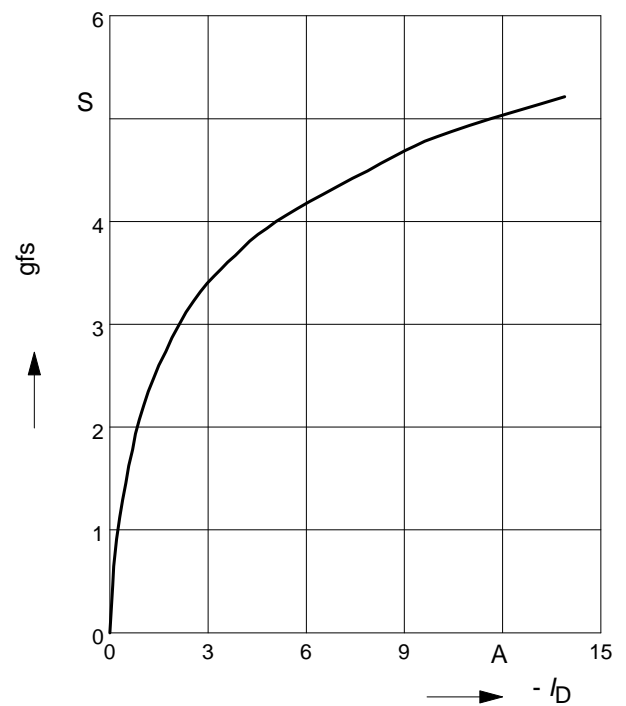
parameter: $t_p = 80 \mu\text{s}$



8 Typ. forward transconductance

$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

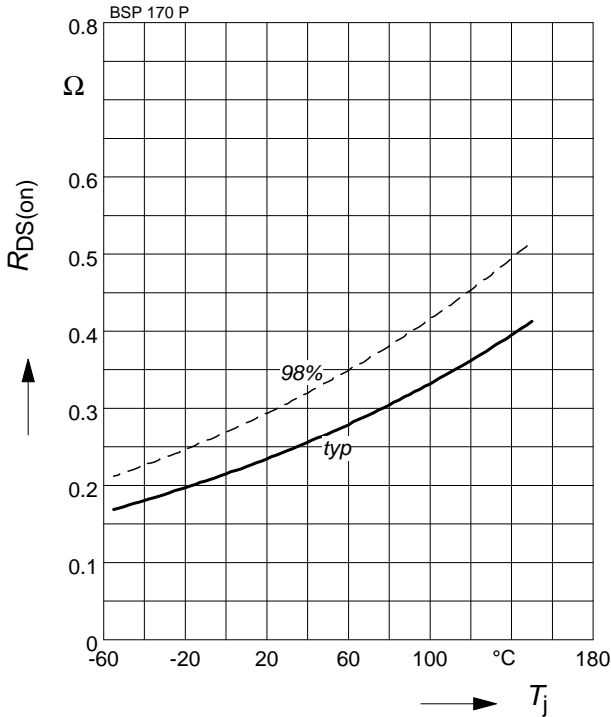
parameter: $t_p = 80 \mu\text{s}$



9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

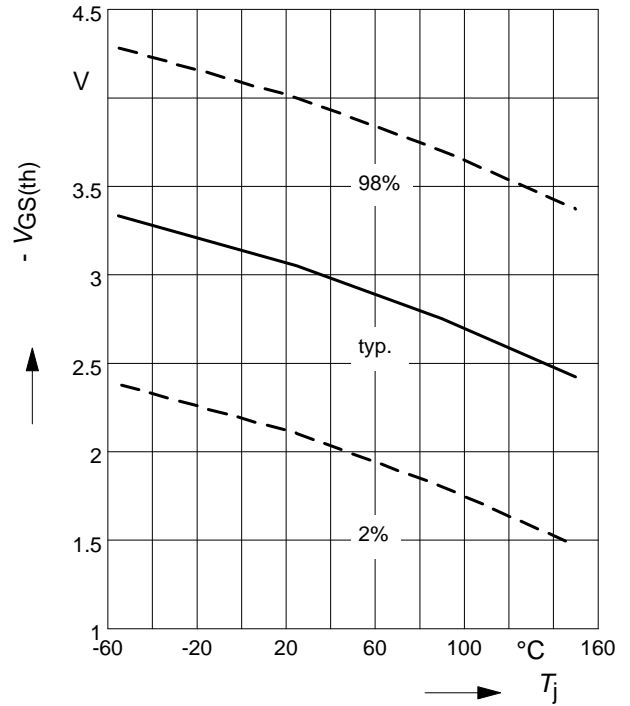
parameter: $I_D = -1.9$, $V_{GS} = -10$ V



10 Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

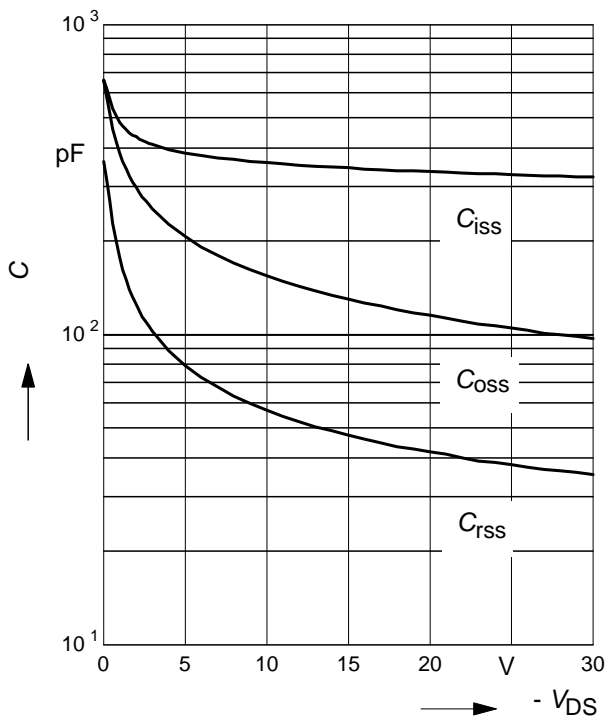
parameter: $V_{GS} = V_{DS}$, $I_D = -250$ μ A



11 Typ. capacitances

$$C = f(V_{DS})$$

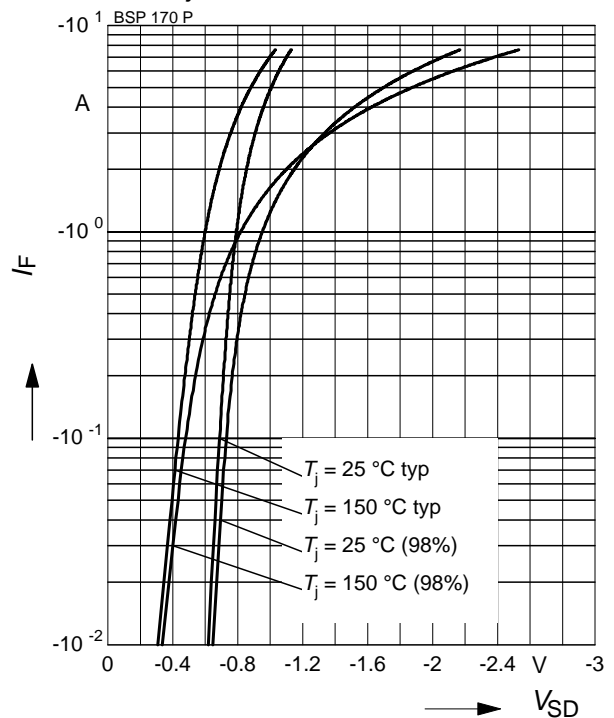
parameter: $V_{GS} = 0$, $f = 1$ MHz



12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

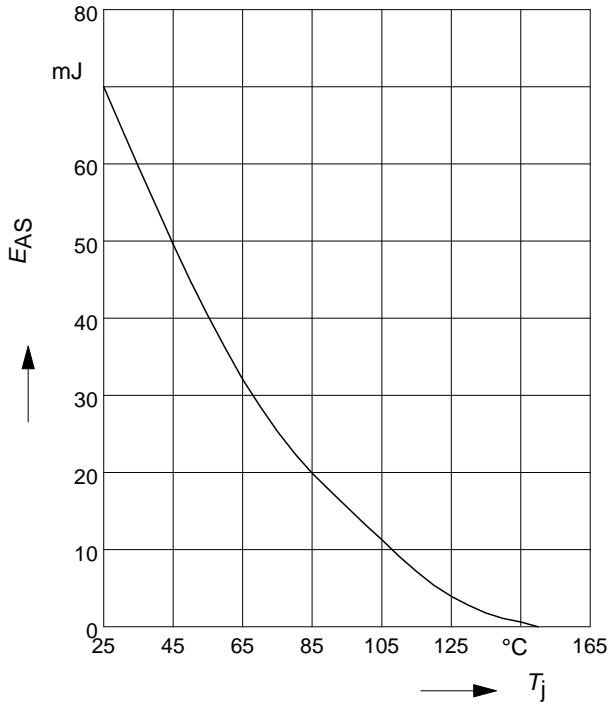
parameter: T_j , $t_p = 80$ μ s



13 Typ. avalanche energy

$$E_{AS} = f(T_j)$$

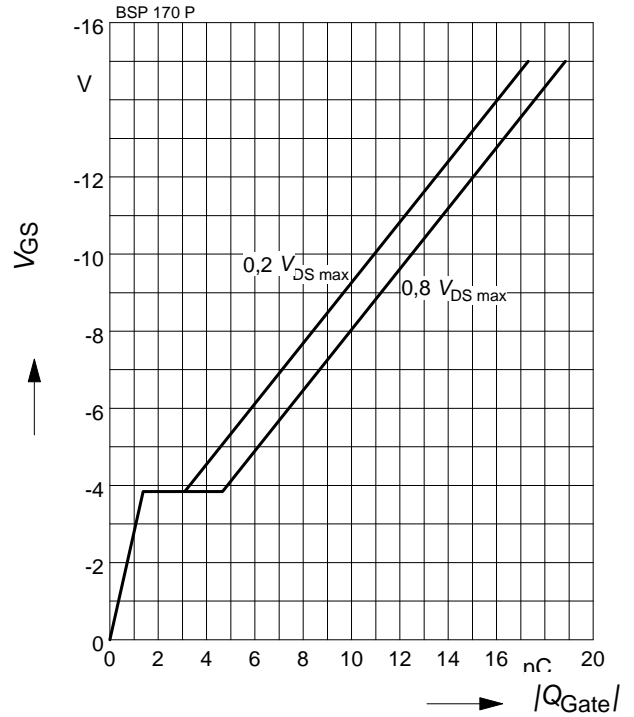
par.: $I_D = -1.9 \text{ A}$, $V_{DD} = -25 \text{ V}$, $R_{GS} = 25 \Omega$



14 Typ. gate charge

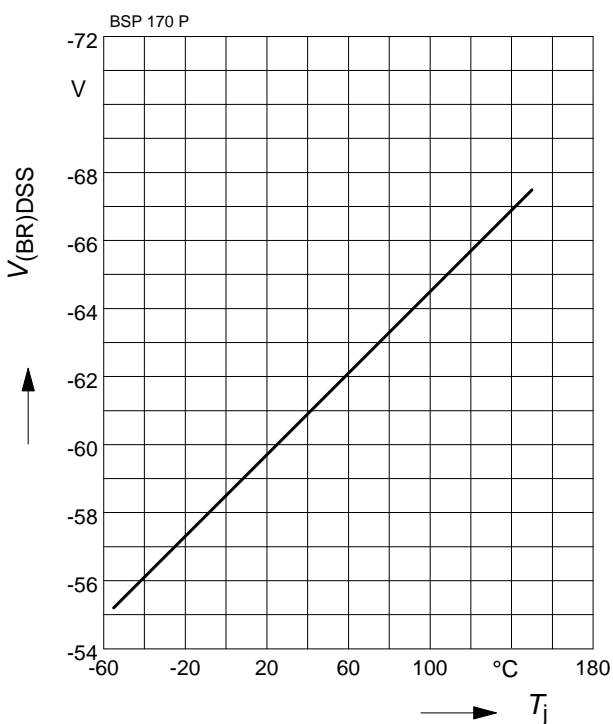
$$V_{GS} = f(Q_{Gate})$$

parameter: $I_D = -1.9 \text{ A}$ pulsed



15 Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$



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